

Title (en)  
MICRO- OR NANO-ELECTRONIC COMPONENT COMPRISING A POWER SOURCE AND MEANS FOR PROTECTING THE POWER SOURCE

Title (de)  
MIKRO ODER NANO-ELEKTRONISCHE KOMPONENTE MIT EINER ENERGIEQUELLE UND MITTEL ZUM SCHÜTZ DER ENERGIEQUELLE

Title (fr)  
COMPOSANT MICRO OU NANO-ELECTRONIQUE COMPORTANT UNE SOURCE D'ENERGIE ET DES MOYENS DE PROTECTION DE LA SOURCE D'ENERGIE

Publication  
**EP 1438748 A2 20040721 (FR)**

Application  
**EP 02795333 A 20021021**

Priority  
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• FR 0113569 A 20011022

Abstract (en)  
[origin: FR2831327A1] A microelectronic or nanoelectronic component including an energy source formed on a substrate (2) incorporates a sealed cavity (9) in which are arranged the parts of the components that are to be protected, these being at least the energy sources (4-7) made up of a microbattery or a microsupercapacitor. A microelectronic or nanoelectronic component including an energy source formed on a substrate (2) incorporates a sealed cavity (9) in which are arranged the parts of the components that are to be protected, these being at least the energy sources (4-7) made up of a microbattery or a microsupercapacitor. The cavity may be under vacuum or filled with an inert gas. A pressure sensor may be arranged inside the cavity and detects a variation in the pressure inside the cavity in order to render the components unusable when the pressure variation passes a predetermined threshold. The cavity may be closed by a cover (10) or filled with a filler material made up of silicon resin, thermohardening resin, polymer, epoxy, fusible glass or by a metal such as indium, tin, lead or their alloys.

IPC 1-7  
**H01L 23/58**

IPC 8 full level  
**G06K 19/073** (2006.01); **H01G 9/00** (2006.01); **H01L 21/48** (2006.01); **H01L 23/20** (2006.01); **H01L 23/26** (2006.01); **H01L 23/58** (2006.01)

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